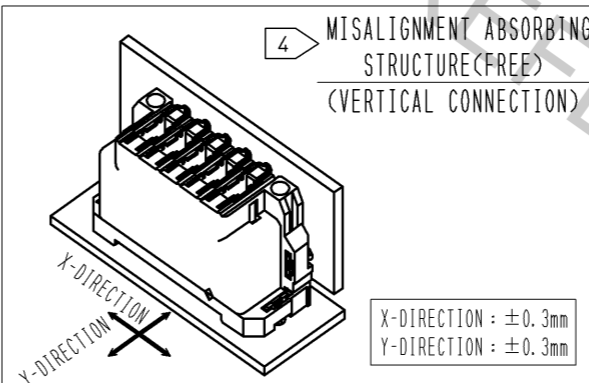


- NOTE
- 1 THIS PRODUCT IS PACKAGED IN TRAY. (25pcs/TRAY)
  - 2 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN'T AFFECT QUALITY LEVEL. ALSO, BLACK SPOT COULD BE OBSERVED ON THE SURFACE OF HOUSING.
  - 3 FOR THE CONTACT NO., ADJACENT TWO PAIRS OF LEADS PLACED BACK-TO-BACK (4 LEADS IN TOTAL) COMPOSE ONE LINE.
  - 4 MISALIGNMENT ABSORBING RANGE: ±0.3mm max.
  - 5 THE DIMENSION IN PARENTHESES ARE FOR REFERENCES.
  - 6 LOT NO. IS INDICATED AT EITHER ONE OF THE POSITION AS SHOWN.
  - 7 POSSIBLE SHORT SHOT AND/OR BURR AT THE INDICATED AREA DOES NOT AFFECT THE PRODUCT QUALITY.

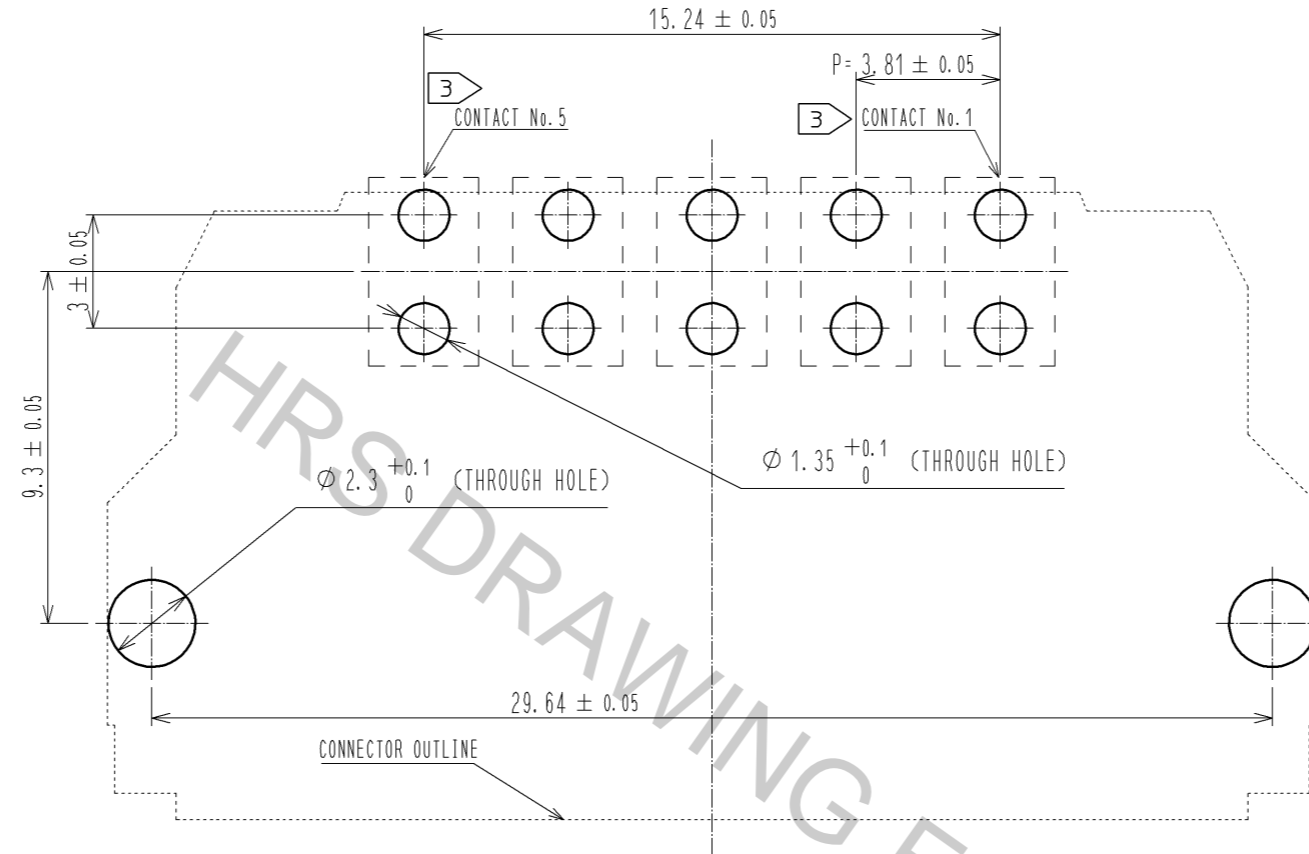


2	COPPER ALLOY	CONTACT AREA:GOLD-PLATING 0.1 μm LEAD AREA:TIN-PLATING 1.0 μm UNDER PLATING:NICKEL 1.0 μm	4	PHOSPHOR BRONZE	TIN-PLATING 3.0 μm UNDER PLATING:NICKEL 1.0 μm
1	POLYAMIDE	BLACK UL94V-0	3	COPPER ALLOY	CONTACT AREA:GOLD-PLATING 0.1 μm LEAD AREA:TIN-PLATING 1.0 μm UNDER PLATING:NICKEL 1.0 μm
5	POLYSTYRENE				

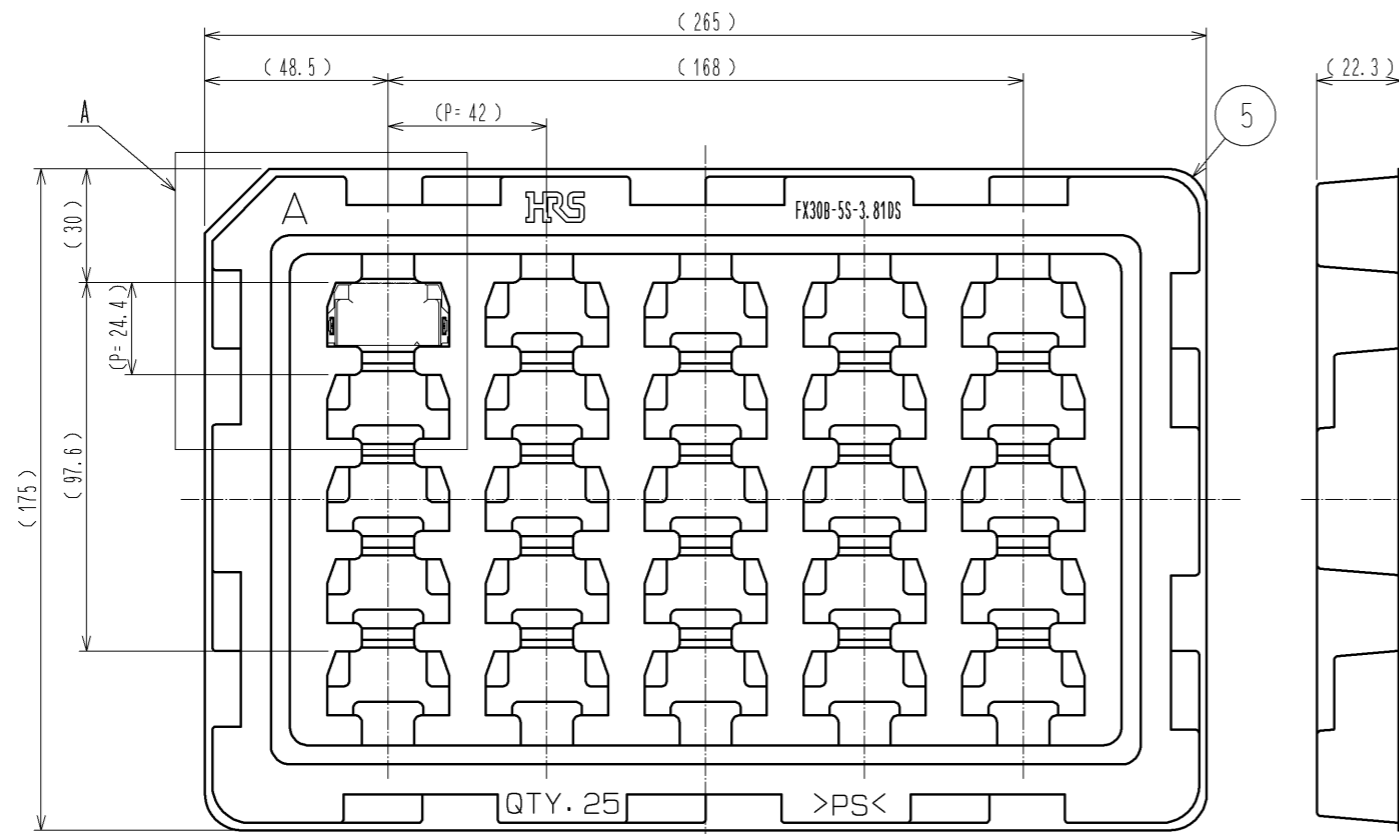
NO.	MATERIAL	FINISH .	REMARKS	NO.	MATERIAL	FINISH .	REMARKS
2	COPPER ALLOY	CONTACT AREA:GOLD-PLATING 0.1 μm LEAD AREA:TIN-PLATING 1.0 μm UNDER PLATING:NICKEL 1.0 μm		4	PHOSPHOR BRONZE	TIN-PLATING 3.0 μm UNDER PLATING:NICKEL 1.0 μm	
1	POLYAMIDE	BLACK UL94V-0		3	COPPER ALLOY	CONTACT AREA:GOLD-PLATING 0.1 μm LEAD AREA:TIN-PLATING 1.0 μm UNDER PLATING:NICKEL 1.0 μm	

UNITS	mm	SCALE	2 : 1	COUNT	△	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
HRS		HIROSE ELECTRIC CO., LTD.		APPROVED	HS. OKAWA	13.03.13	DRAWING NO. EDC3-347279-00		
		CHECKED	KI. HIROKAWA	13.03.12	PART NO. FX30B-5S-3.81DS				
		DESIGNED	DK. AIMOTO	13.03.11	CODE NO. CL570-3603-4-00				
		DRAWN	DK. AIMOTO	13.03.11				1/2	

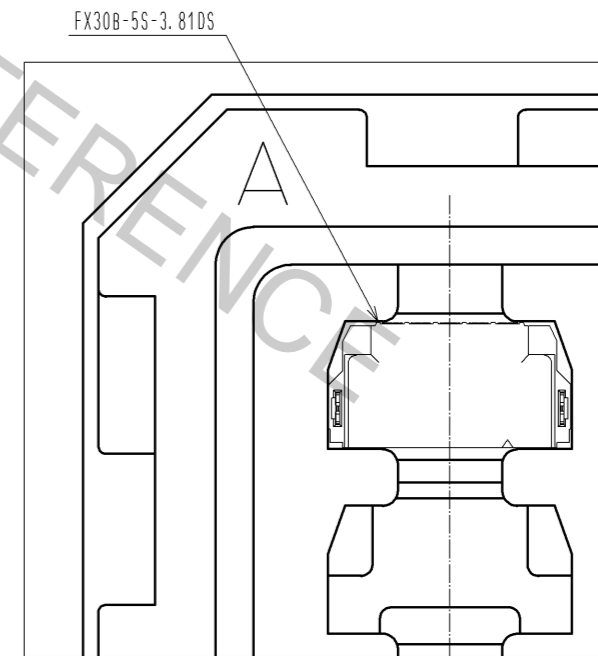
RECOMMENDED HOLE PATTERN DIMENSION OF PCB(5:1)  
(CONNECTOR MOUNTING SIDE, PCB THICKNESS:t=1.6mm)



1 DRAWING FOR PACKAGING(1:2)



A(1:1)



<b>HRS</b>	DRAWING NO.	EDC3-347279-00		2/2
	PART NO.	FX30B-5S-3.81DS		
	CODE NO.	CL570-3603-4-00		